



XPX6602RD

## N-Channel Enhancement Mode Power MOSFET



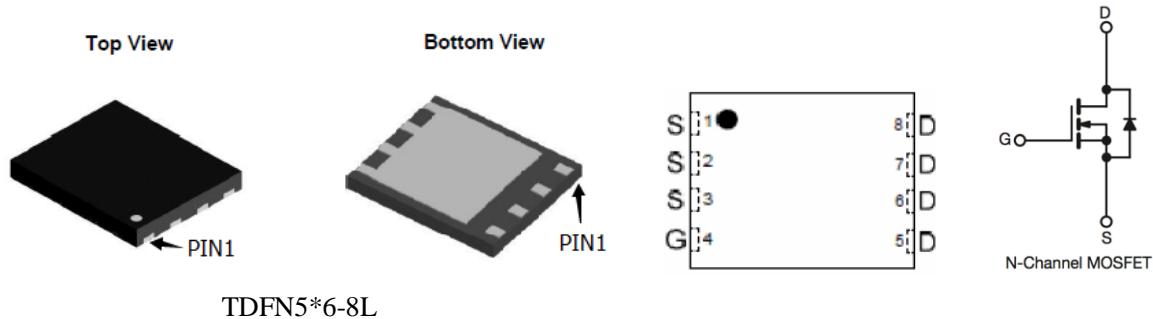
## ● Features

$V_{DS} = 60V$ ,  
 $I_D = 150A$   
 $R_{DS(ON)} @ V_{GS} = 10V, TYP 2.6m\Omega$   
 $R_{DS(ON)} @ V_{GS} = 4.5V, TYP 3.8m\Omega$

## ● General Description

- Notebook AC-in load switch
- Battery protection charge/discharge

## ● Pin Configurations



TDFN5\*6-8L

● Absolute Maximum Ratings @  $T_A=25^\circ C$  unless otherwise noted

Parameter		Symbol	Ratings	Unit
Drain-Source Voltage		$V_{DSS}$	60	V
Gate-Source Voltage		$V_{GSS}$	$\pm 20$	V
Drain Current (Continuous) *AC	$T_c=25^\circ C$	$I_D$	150	A
	$T_c=70^\circ C$		120	
Drain Current (Pulse) *B		$I_{DM}$	200	A
Power Dissipation	$T_c=25^\circ C$	$P_D$	83	W
Operating Temperature/ Storage Temperature		$T_J/T_{STG}$	-55~150	°C

## ● Thermal Resistance Ratings

Parameter		Symbol	Typical	Maximum	Unit
Maximum Junction-to-Ambient	$t \leq 10 s$	$R_{thJA}$	18	23	°C/W
Maximum Junction-to-Case (Drain)	Steady State	$R_{thJC}$	1	1.5	

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● **Electrical Characteristics @ $T_A=25^\circ C$**  unless otherwise noted

Parameter	Symbol	Test Conditions	Min	Typ	Max	Unit
<b>Static</b>						
Drain-Source Breakdown Voltage	$V_{(BR)DSS}$	$V_{GS} = 0V, I_D = 250\mu A$	60	--	--	V
Zero Gate Voltage Drain Current	$I_{DSS}$	$V_{DS} = 60 V, V_{GS} = 0V$	--	--	1	$\mu A$
Gate Threshold Voltage	$V_{GS(TH)}$	$V_{GS} = V_{DS}, I_{DS} = 250\mu A$	1	1.7	2.5	V
Gate Leakage Current	$I_{GSS}$	$V_{GS} = \pm 20V, V_{DS} = 0V$	--	--	$\pm 100$	nA
Drain-Source On-state Resistance	$R_{DS(on)}$	$V_{GS} = 10V, I_D = 20A$	--	2.6	3.3	$m\Omega$
	$R_{DS(on)}$	$V_{GS} = 4.5V, I_D = 20A$	--	3.8	4.8	$m\Omega$
Diode Forward Voltage	$V_{SD}$	$I_{SD} = 1A, V_{GS} = 0V$	--	0.77	1.2	V
Diode Forward Current *AC	$I_S$	$T_C = 25^\circ C$	--	--	120	A
<b>Switching</b>						
Total Gate Charge	$Q_g$	$V_{DS} = 30 V, V_{GS} = 10 V, I_D = 10 A$	--	45	--	nC
Gate-Source Charge	$Q_{gs}$		--	9	--	nC
Gate-Drain Charge	$Q_{gd}$		--	5	--	nC
Turn-on Delay Time	$t_{d(on)}$	$V_{DD} = 30 V, R_L = 3\Omega, I_D = 10 A,$ $V_{GEN} = 10 V, R_g = 1\Omega$	--	15	--	ns
Turn-on Rise Time	$t_r$		--	9	--	ns
Turn-off Delay Time	$t_{d(off)}$		--	32	--	ns
Turn-Off Fall Time	$t_f$		--	8	--	ns
<b>Dynamic</b>						
Input Capacitance	$C_{iss}$	$V_{DS} = 30 V, V_{GS} = 0V, f = 1.0 MHz$	--	4220	--	pF
Output Capacitance	$C_{oss}$		--	1406	--	pF
Reverse Transfer Capacitance	$C_{rss}$		--	113	--	pF

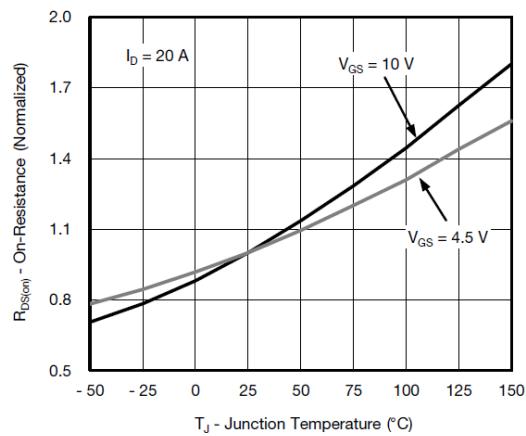
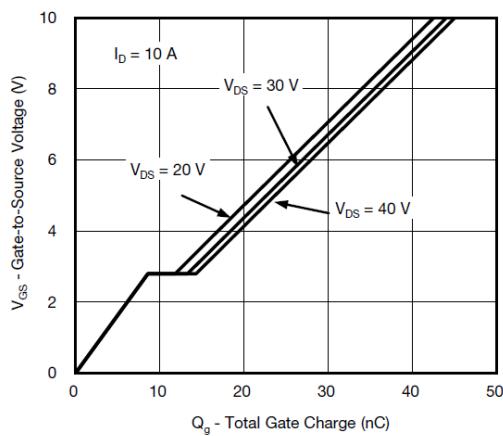
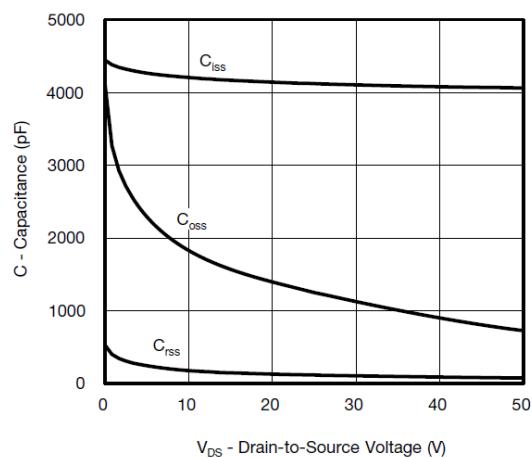
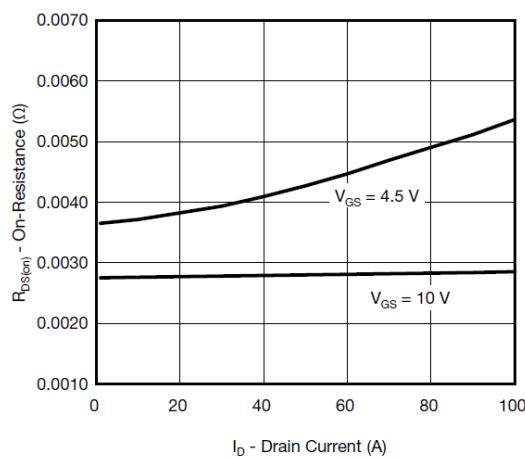
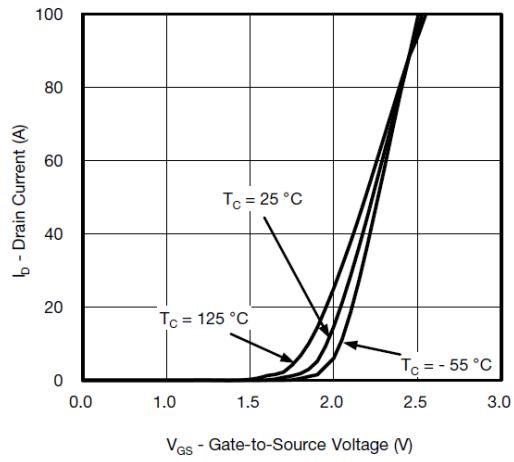
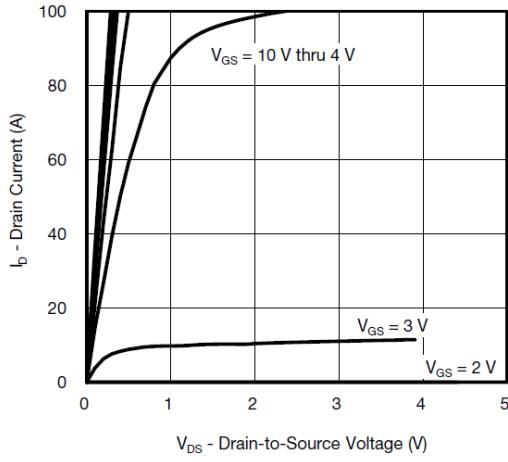
A: The value of  $R_{\theta JA}$  is measured with the device mounted on 1in<sup>2</sup> FR-4 board with 2oz. Copper, in a still air environment with  $T_A=25^\circ C$ . The value in any given application depends on the user's specific board design.

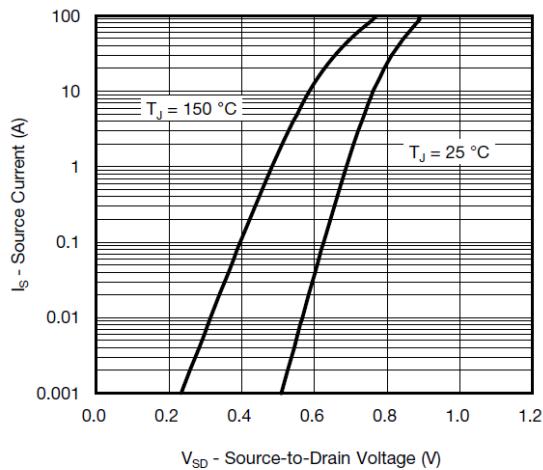
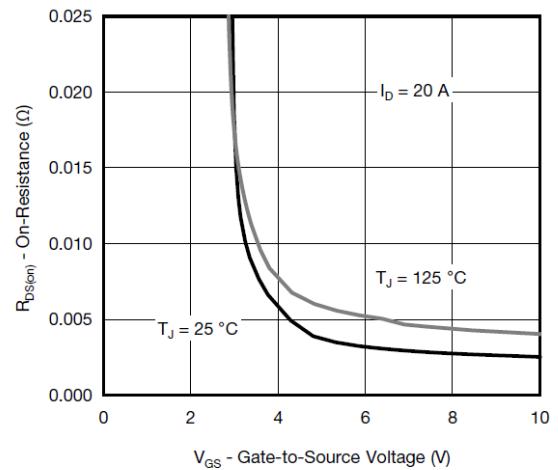
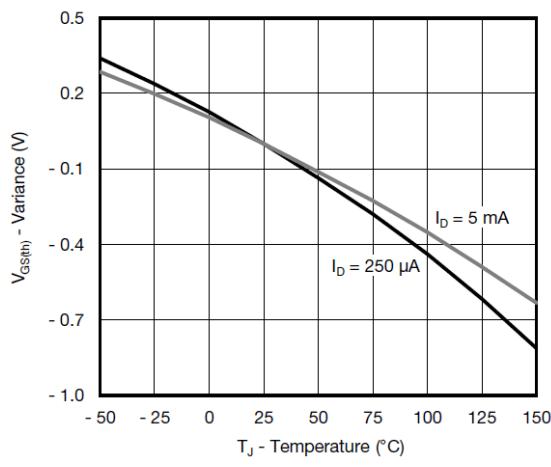
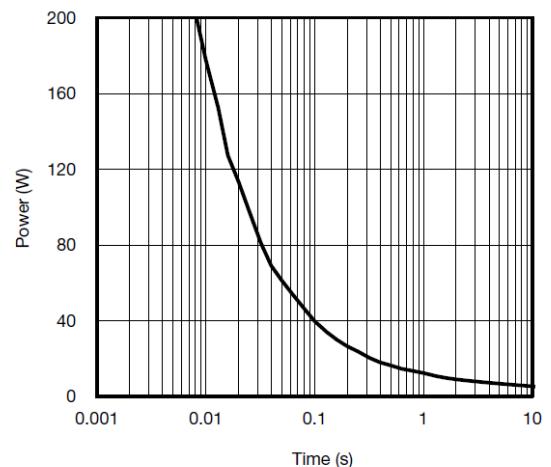
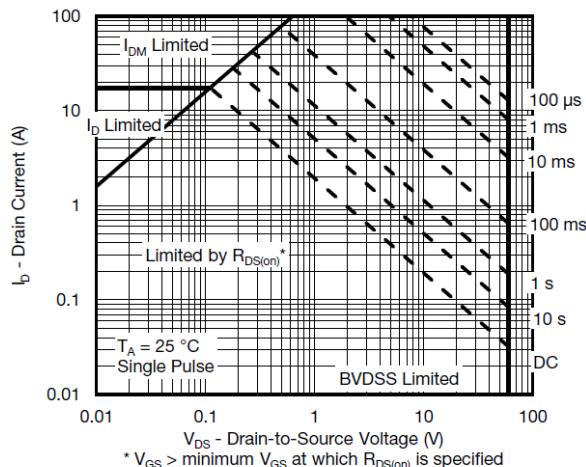
B: Repetitive rating, pulse width limited by junction temperature.

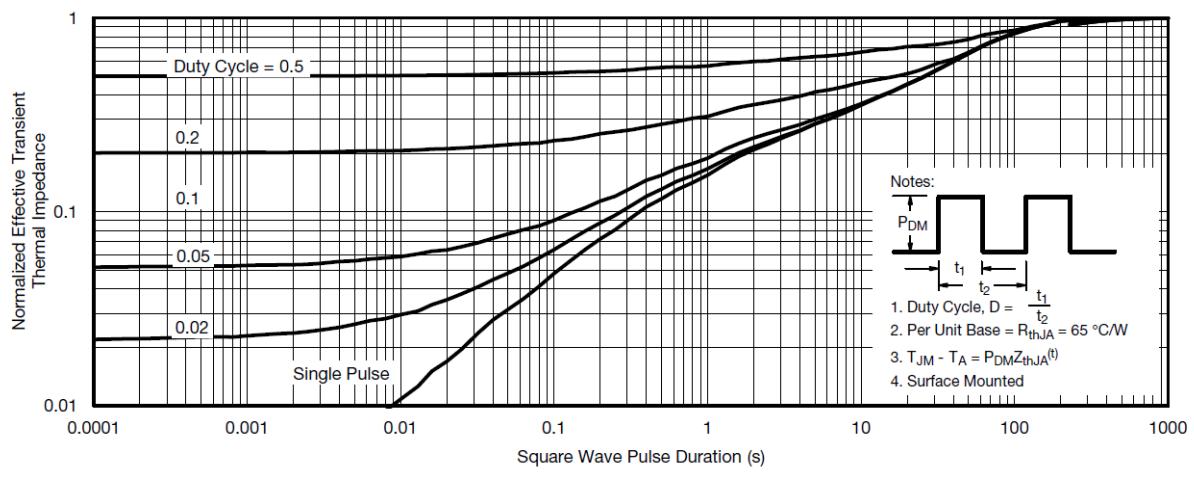
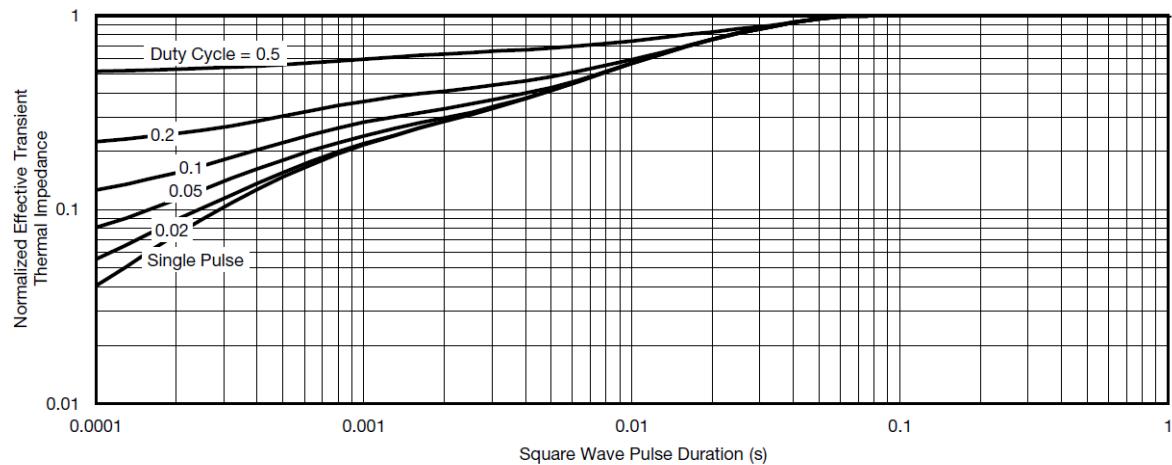
C: The current rating is based on the  $t \leq 10s$  junction to ambient thermal resistance rating, Package limited 120A.

**N-Channel Enhancement Mode Power MOSFET**


- Typical Performance Characteristics ((T<sub>J</sub> = 25 °C, unless otherwise noted))**



**N-Channel Enhancement Mode Power MOSFET**

**Source-Drain Diode Forward Voltage**

**On-Resistance vs. Gate-to-Source Voltage**

**Threshold Voltage**

**Single Pulse Power, Junction-to-Ambient**

**Safe Operating Area, Junction-to-Ambient**


**Normalized Thermal Transient Impedance, Junction-to-Ambient**

**Normalized Thermal Transient Impedance, Junction-to-Case**

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● **Package Information**
